

Webinar

Power the Future: Selecting and Designing Power Components for AMD Versal™ AI Edge Series

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AMD VERSAL™ ARCHITECTURE POWER IMPROVEMENTS

Programmable Logic:

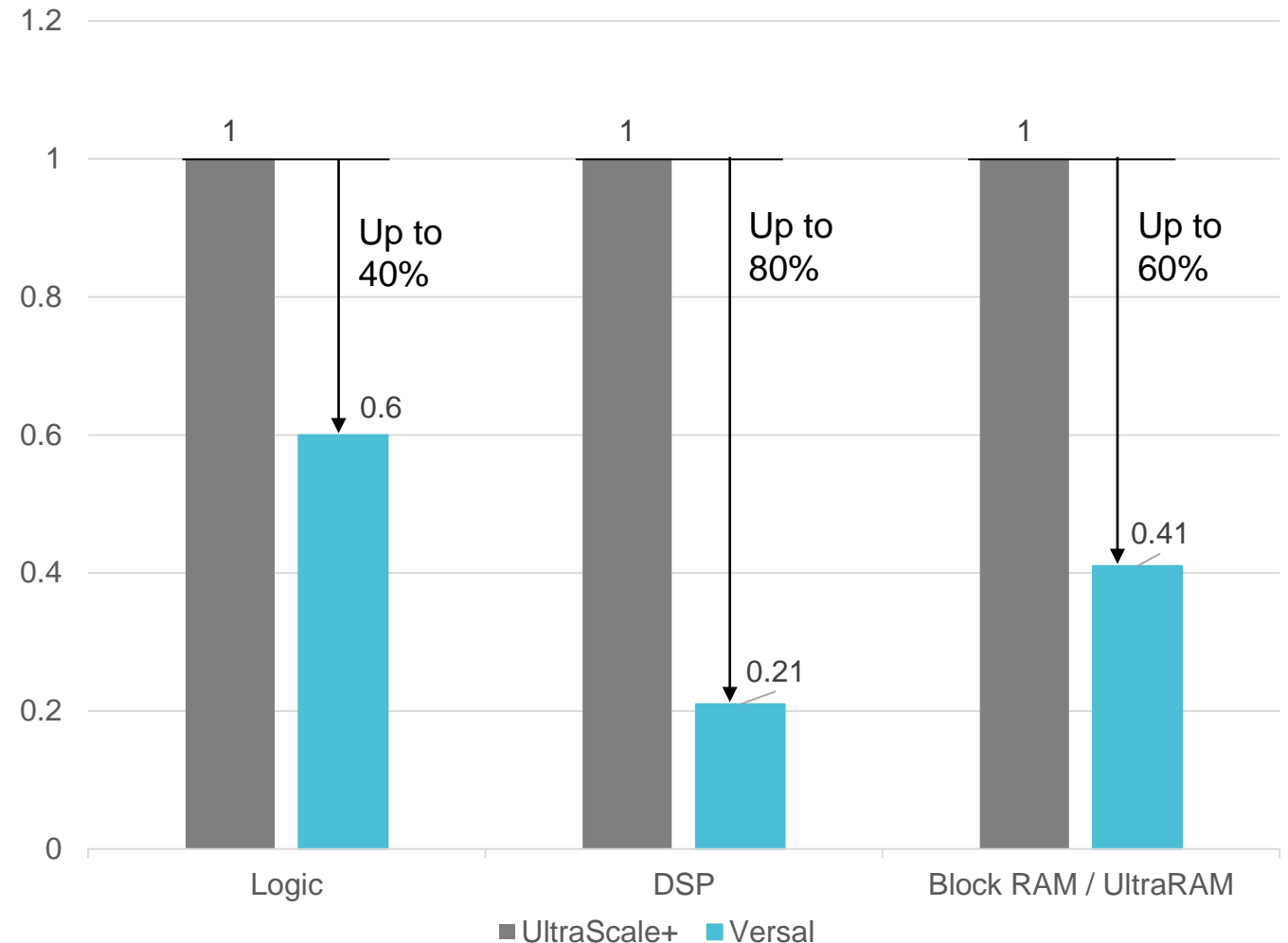
- Up to 40% lower power depending on LUT implementation: Logic, Distributed RAM, Shift Reg, or Register

DSP

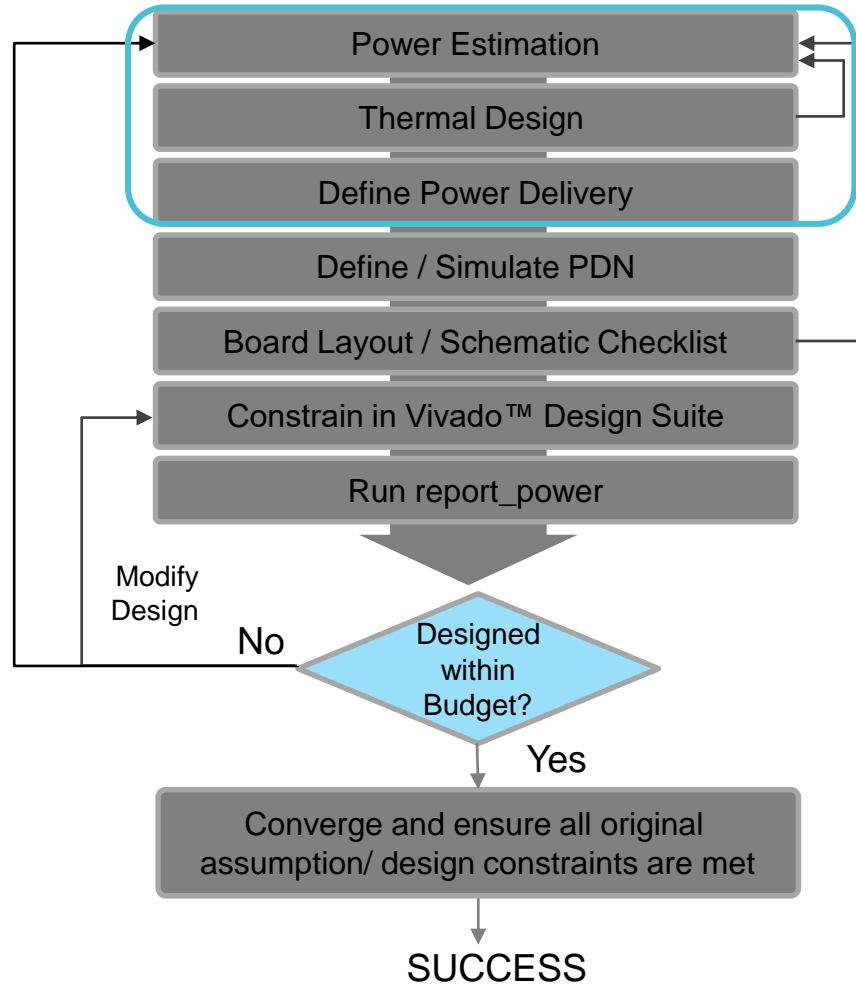
- Up to 80% reduction for floating point operations: DSP58 vs. DSP48

Block RAM / UltraRAM

- Continued power reduction in AMD Versal™ adaptive SoCs compared to AMD UltraScale+™ FPGAs



Versal™ Devices' Power Design Flow



The screenshot shows the Vivado Power Design Suite interface for a Versal AI Edge Series device (XCVE2602-VSVH1760-2MP-E-S). The left sidebar displays a tree view with categories: Summary, Estimation, Power Design, and Power Management. The 'Estimation' category is expanded, showing a list of power components and their percentages of total power. The 'Power Design' category is also expanded, showing a list of power design tasks. The main window displays the 'Part' configuration page, which includes fields for Family, Package, Temperature, Device Grade, Speed, VCCINT Voltage, and Process. The 'Summary' table provides a detailed breakdown of power consumption, and the 'Environment' table shows thermal parameters. The 'DFX' section at the bottom provides information about Design for Manufacturability (DFX) usage.

| Category | Item | Value |
|------------------|--------------------------|----------------------------|
| Estimation | PS | 0.528 W, 0.68 % |
| | NoC/DDRMC | 3.248 W, 4.18 % |
| | Clock | 3.474 W, 4.55 % |
| | Logic | 4.089 W, 5.35 % |
| | Block RAM | 0.245 W, 0.32 % |
| | UltraRAM | 0.63 W, 0.81 % |
| | DSP | 0.821 W, 1.06 % |
| | I/O | 3.247 W, 4.18 % |
| | GTYP | 5.099 W, 6.56 % |
| | AI Engine-ML | 42.103 W, 54.54 % |
| Hard IP Blocks | 3.073 W, 3.94 % | |
| Power Design | Part | |
| | Power Summary | |
| | Power Rail Consolidation | |
| | Power Supply Summary | |
| | Power Supply Design | |
| | Characterization | Advance (+/- 25% accuracy) |
| Power Management | Summary of Savings | |
| | Clock Domain Power | |
| | Potential Savings | |

| Summary | Value |
|---|----------------------------|
| Total On-Chip Power | 76.366 W |
| Static Power | 9.680 W |
| Dynamic Power | 66.686 W |
| Junction Temperature | 70 C |
| Thermal Margin | 30 C |
| Thermal Power Margin | |
| Thermal Power Margin with excursion to 110C | |
| Characterization | Advance (+/- 25% accuracy) |

| Environment | User Override ON | Value |
|--|------------------|-----------|
| Junction Temperature | | 70 C |
| Ambient Temperature | | 25 C |
| Effective Theta JA | | 0.000 C/W |
| Max. Junction Temperature | | 100 C |
| Max. Junction Temperature with Excursion to 110C | | 110 C |
| Design Power Budget | | |

| DFX | Value |
|-----------|---|
| DFX Usage | DFX with 1 RP that includes NoC resources |

Introduction to the Power Design Tab of PDM

Device Characteristics

- Summary of device details
 - Part number, speed & temperature grade, process information, packaging
- Static, dynamic, and total device power
- Export to .xml file
- Import XPE files to PDM

Power Supply Design Table

- Individual rail characteristics by power domain
 - Rail names
 - Voltage tolerances
 - Static, dynamic, and power-up current requirements
 - Sequencing
 - Step load values

Power Rail Consolidations

- Full power management
 - Selected to allow for powering down of rails
- Minimum Rails
 - Reduces overall regulator count at the expense of power management
- Rail consolidation diagrams, power sequencing & tables

| Part | |
|----------------|-----------------------|
| Family | Versal AI Edge Series |
| Device Grade | XC |
| Device | XCVE2602 |
| Package | VSVH1760 |
| Speed | 2 |
| Static Power | S |
| Temperature | E |
| VCCINT Voltage | MP |
| Process | Maximum |

| Power Summary | |
|---------------|----------|
| Total | 76.366 W |
| Static | 9.680 W |
| Dynamic | 66.686 W |

| ge | Min Voltage | Max Voltage | Step Load % | Static (A) | Dynamic (A) | Total (A) |
|-------|-------------|-------------|-------------|------------|-------------|-----------|
| 0.800 | 0.775 | 0.825 | 33.00 % | 0.022 | 0.000 | 0.022 |
| 1.500 | 1.455 | 1.545 | 33.00 % | 0.833 | 0.014 | 0.846 |
| 0.800 | 0.775 | 0.825 | 33.00 % | 0.347 | 0.000 | 0.347 |
| 0.800 | 0.775 | 0.825 | 33.00 % | 0.036 | 0.000 | 0.036 |
| 0.800 | 0.775 | 0.825 | 25.00 % | 2.071 | 0.008 | 2.080 |
| 0.800 | 0.775 | 0.825 | 33.00 % | 0.011 | 0.000 | 0.011 |

Power Design Tab (Cont.)

Power Supply Design Table

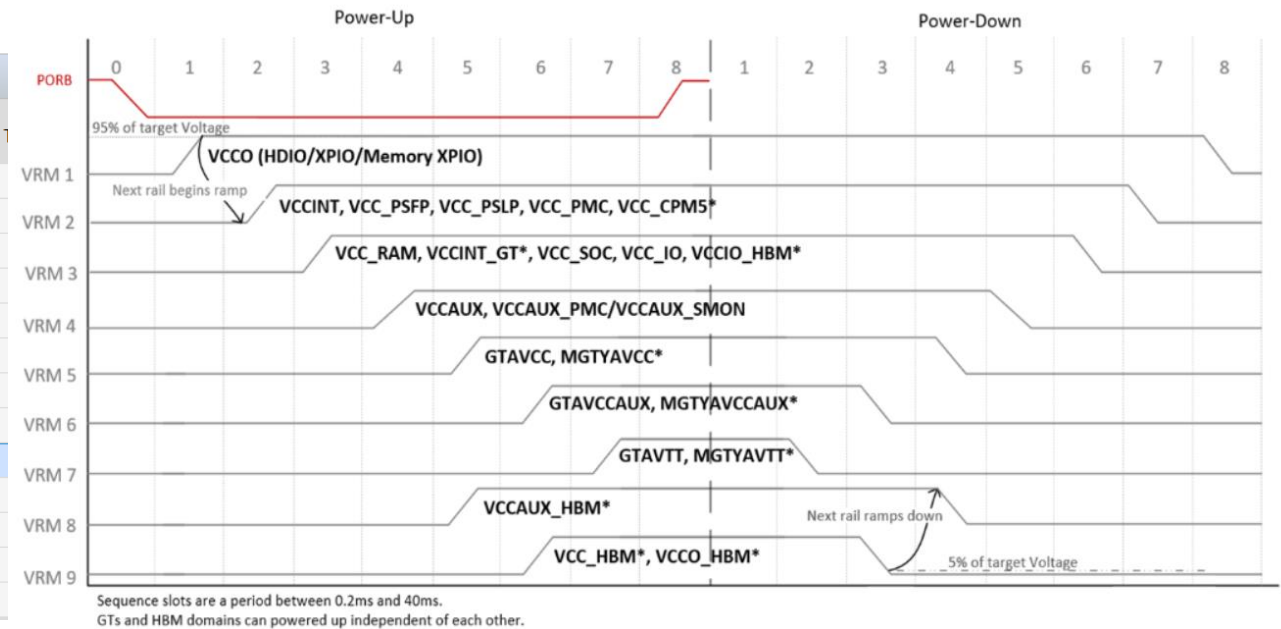
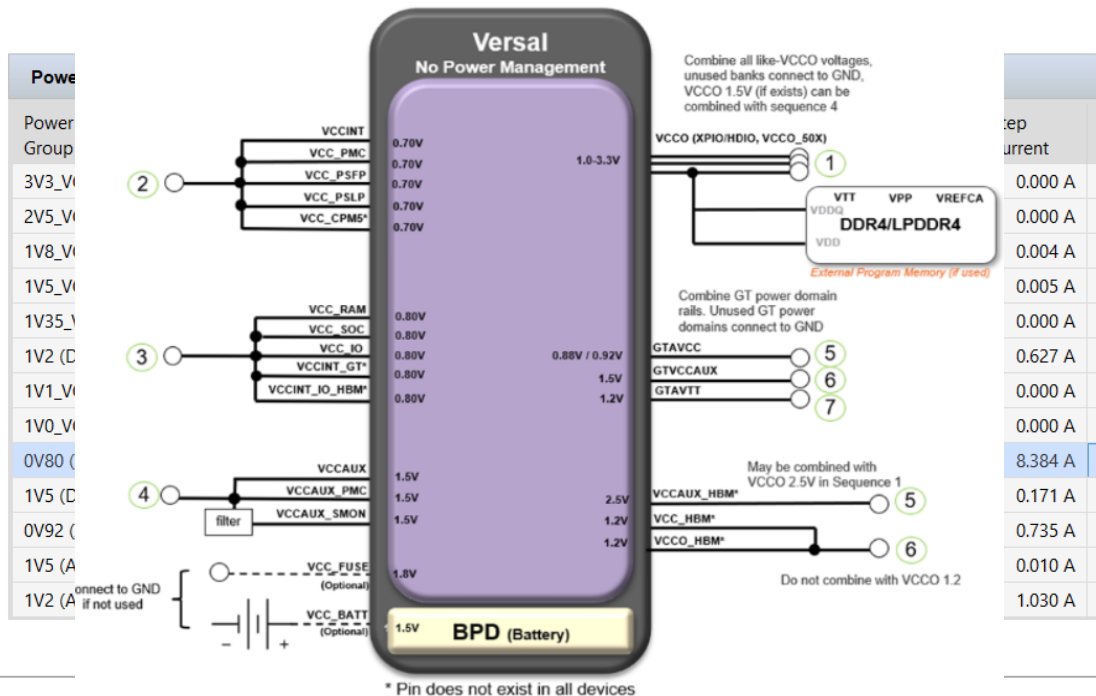
- Grouping of rails by group name
- Power sequence
- Combined power rail current requirements & tolerances
- Voltage regulator current capability entry

Decoupling Capacitor Details

- Dynamic decoupling recommendations
- XQ and XC temperature ranges
- Capacitor P/Ns, values, and placement techniques
- ESR, ESL information to aid alternative capacitor selection

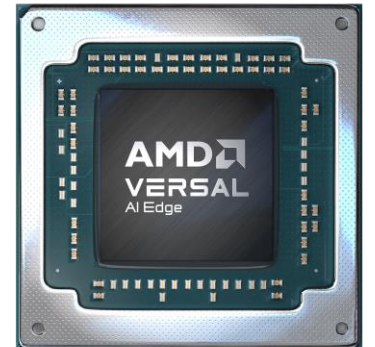
Sequencing/Rail Diagrams

- Power-up & down sequencing by rail grouping
- Timing and ramping requirements
- POR_B pull down timings
- Conditions for next rail power up



Summary

- Versal™ architecture's power improvements and new tools make power delivery more convenient
- Understanding the power design tab in PDM can ensure a successful power delivery design
- Download Power Design Manager from the AMD power delivery webpage www.amd.com/power
- Import designs from XPE to PDM if still using XPE
- Utilize the export .xml feature and submit your file to AMD's power delivery partners
- Example of Voltage regulator design for V_{CCINT}
- V_{CCINT} powers the programmable logic, AI Engines, and other internal blocks in Versal™ devices
- When using Minimum Rails consolidation, we combine V_{CCINT} with other like voltages
 - V_{CCINT} , V_{CC_RAM} , V_{CC_PSFP} , V_{CC_PSLP} , V_{CC_PMC}
 - Power Supply Design table combines the current requirements of all rails



Endnotes

VER-043

Based on an AMD dynamic performance per watt comparison of the 7nm -2L Versal™ device architecture and the 16nm -2 Virtex UltraScale+ device architecture in February 2024, using the production-stage versions of the AMD Power Design Manager 2023.2. tool and XPE 2023.1.2 tool to measure the power per watt of the programmable logic, DSP Engines, Block RAM, UltraRAM, gigabit transceivers, and DDR memory controllers. Results may vary based on a variety of factors, including customer application design, implementation, and data inputs.

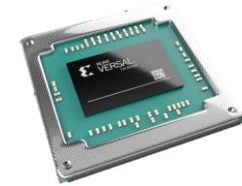
Introduction to Core Power Supply

This webinar will help you

- Use AMD Power Design Manager tool and export data to start your power journey
- Choose the right TI part and Wuerth Elektronik inductor (passive) to maximise efficiency and minimize passive components in your high power density applications
- Use TI's WEBENCH® and RED EXPERT online tools to simulate the performance of your circuit

Some featured products

AMD Versal™ AI Edge Series



Texas Instruments TPS6287B25, 25-A Step-Down Converter



**Wuerth Elektronik
74435030010 Series Ultra-Low Loss
Shielded Power Inductors**



Agenda

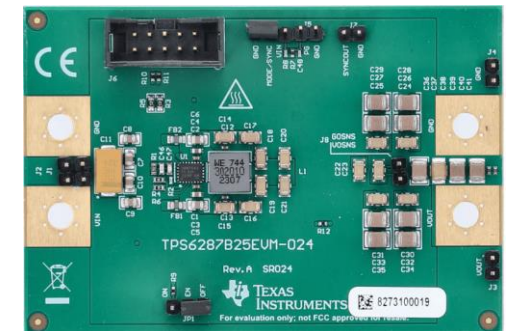
- How to interpret AC + DC specification of a processor
- Maintaining a high voltage accuracy at DC and during load transients.
- Design Example using the latest VE2302 applications
- How to optimize the load transient performance

Some featured products

AMD Versal™ AI Edge Series



Texas Instruments TPS6287B25, 25-A Step-Down Converter



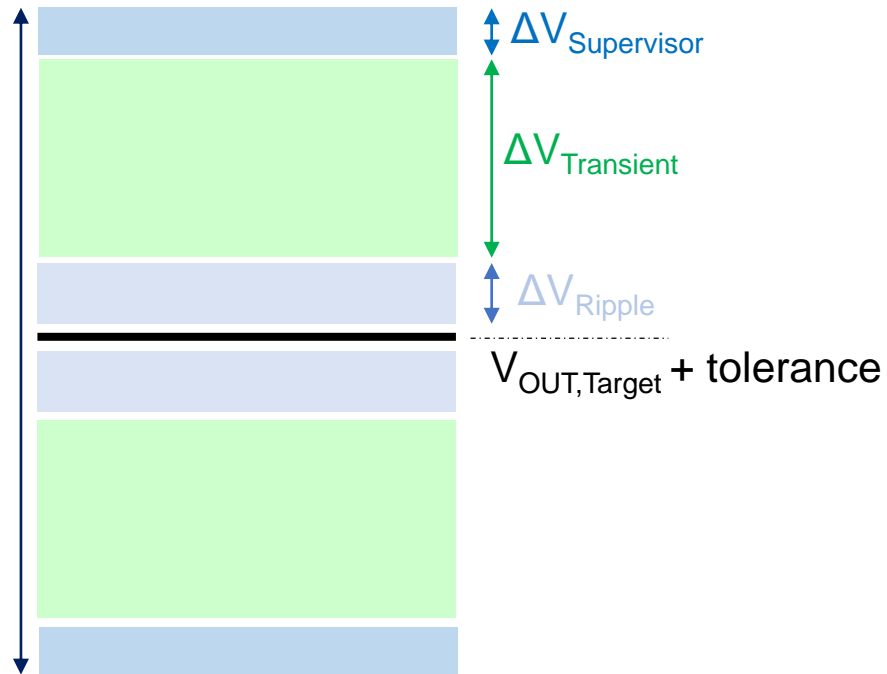
**Wuerth Elektronik
74435030010 Series Ultra-Low Loss
Shielded Power Inductors**



Power Design Manager Output data for VE2302

| Rail Name | Voltage | DC Spec. | AC Spec. | Current | Step | Sequence # |
|--|---------|----------|----------|---------|------|------------|
| VCCINT/VCC_PMC/VCC_PSFP/ VCCPSLP/VCC_RAM/VCC_SOC/ VCC_IO | 0.8 V | ±1% | ±17mV | 39 A | 33% | 2 |
| VCCO | 1.5 V | ±1% | ±5% | 3 A | 100% | 1 |
| VCCAUX/VCCAUX_PMC/ VCCAUX_SMON | 1.5 V | ±1% | 10mVpp | 1.1 A | 100% | 3 |
| GTAVCC | 0.88 V | ±2% | 10mVpp | 0.7 A | 70% | 4 |
| GTAVTT | 1.2 V | ±2% | 10mVpp | 1.3 A | 70% | 6 |
| GTAVCCAUX | 1.5 V | ±2% | 10mVpp | 0.05 A | 70% | 5 |

$\Delta V_{OUT} = 34\text{mVpp}$
 AC spec
 Recommended
 $C_{OUT} = 1065 \mu\text{F}$



- Load Step Currents
- Min/Max Voltage Requirements
- Ripple Requirements
- Voltage for External Supervisor required?
- Max Current (DC and peak)
- DC accuracy (with remote sense)

Load transient is largest contributor to output voltage accuracy → drives output capacitance requirement

TPS62 87Bx

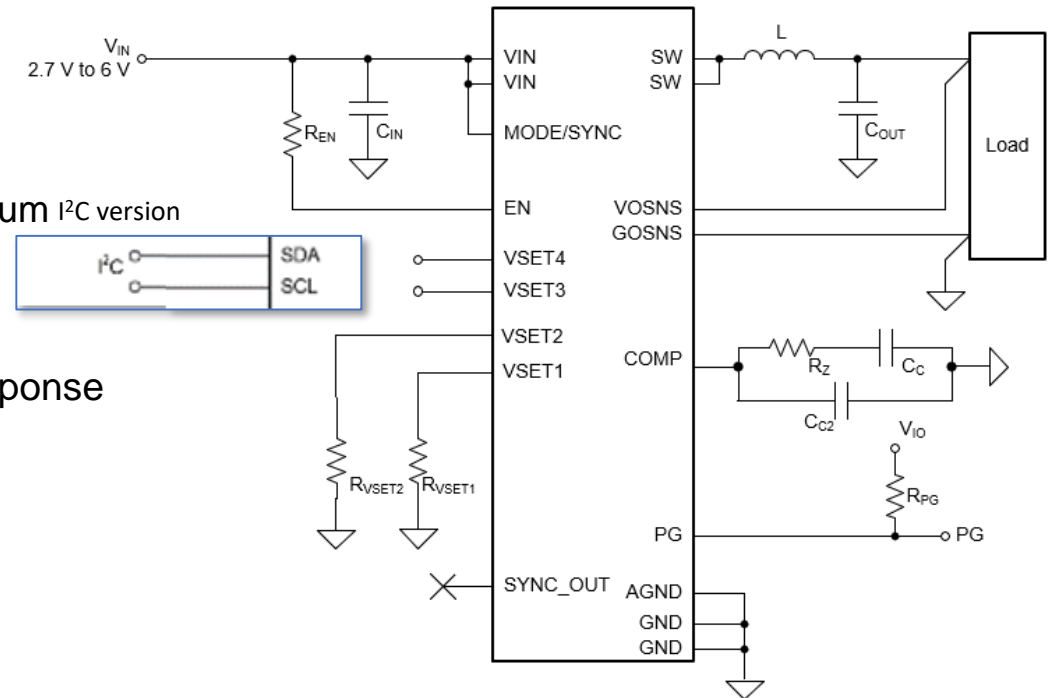
6V_{IN}, 10A to 25A Buck Converter with Remote Sense, Stackable

Features

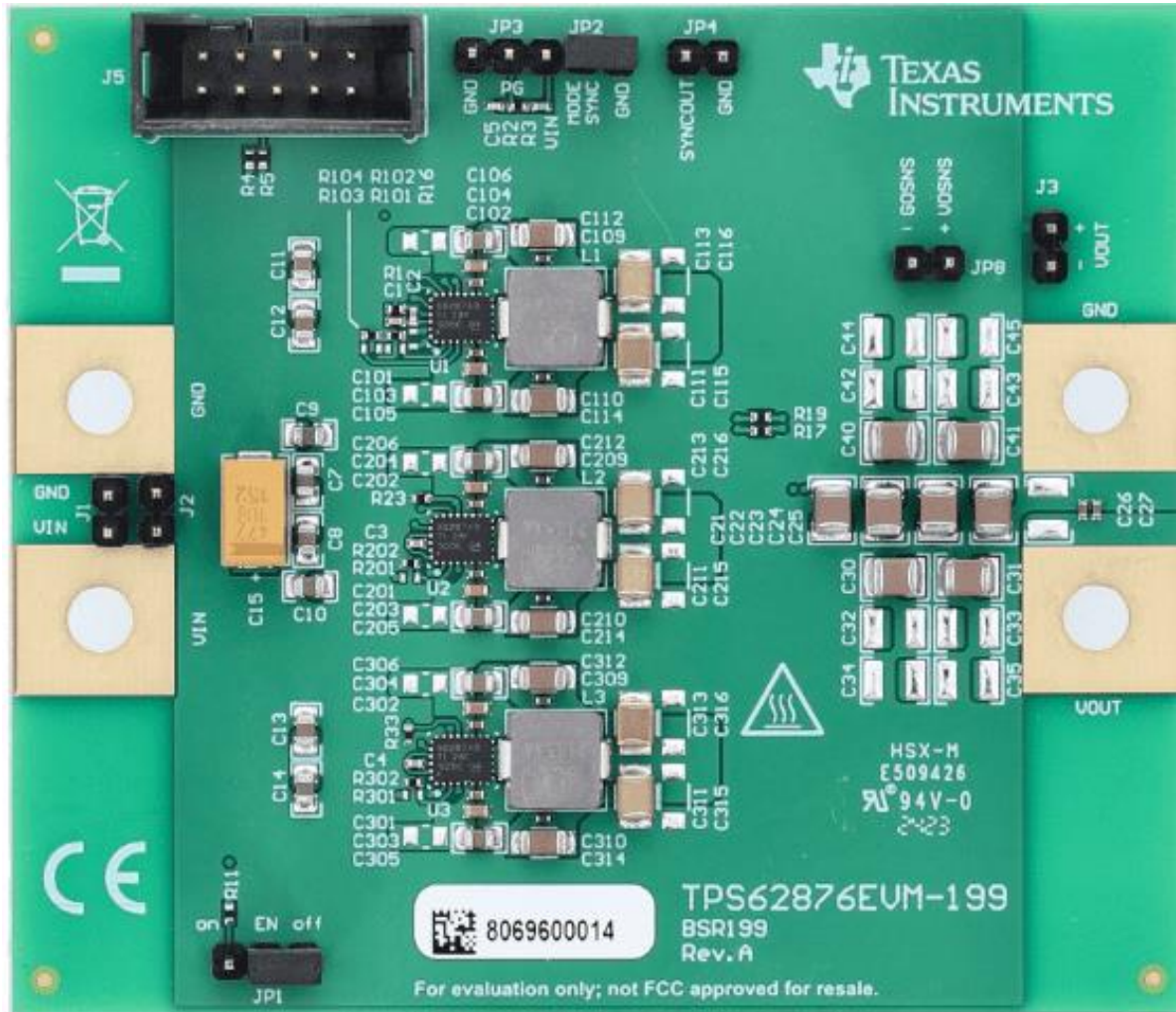
- 2.7V to 6.0V input voltage
- Low R_{DS(ON)} Switches 2.6mΩ / 1.5mΩ
- Output voltage accuracy: ±0.8%
- Family with 10A, 15A, 20A, 25A (stackable to higher currents)
- **I²C version:** 2 x 16 V_{OUT} startup voltage options selectable:
 - Low output voltage range 0.4V – 0.775V in 25 mV steps
 - High output voltage range 0.8V – 1.55V in 50 mV steps
 - Dynamic Voltage Scaling in 1.25mV – 5mV steps
 - Temperature Warning, Voltage Monitoring, SoftStart, Spread Spectrum I²C version
- **V_{SET} version:** 64 selectable V_{OUT} options
 - 0.4V – 1.675V (in 25mV steps)
- Remote differential sense at load for high accuracy & fast transient response
- Droop compensation (optional)
- 1.5MHz switching frequency
- Forced-PWM or Automatic Power Save Mode
- Functional Safety Capable
- 3.05 x 4.05mm QFN

Benefits

- High output current with small solution size
- Remote sense for Core supply
- Stackability to allow for smaller inductors and better heat distribution
- Dynamic adaptation to processor loads, adjustable output voltage

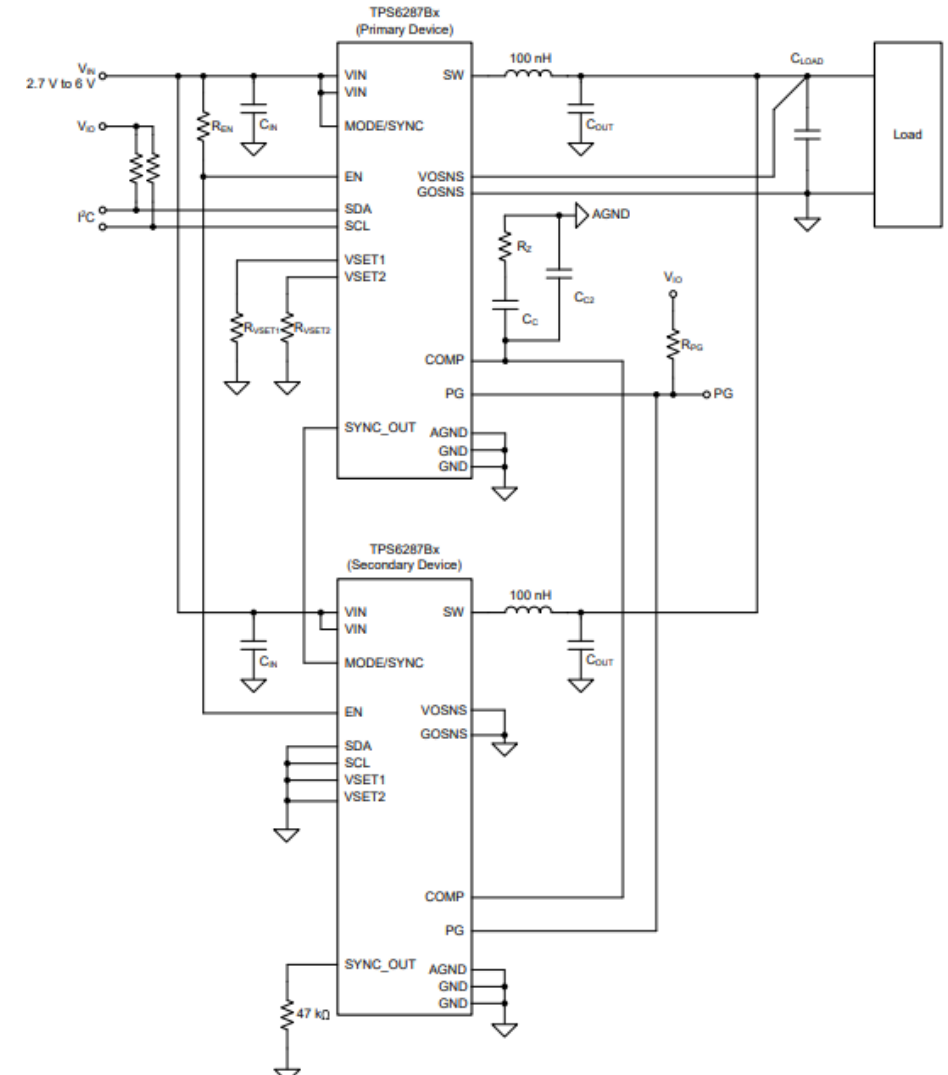


Output can be paralleled to support greater load currents



To optimize design

<https://webench.ti.com/power-designer/>



75 A EVM with 3x TPS62876-Q1

WEBENCH Power Designer Inputs

Customize TPS6287B25LA0WRZV - 2.7V-6V to .75V @ 19.5A

Input: DC 4.5 V - 5.5 V Output: 0.8 V at 19.5 A Temp: 30 °C [Change](#)

Summary

Efficiency: 89.7%
BOM Cost: \$4.17
Footprint: 267 mm²

CHANGE OPTIMIZATION

Configuration Options

Mode of Operation

FPWM

Custom Sync Frequency

Sync Frequency

1.5 MHz

(1.3 - 1.8)

Asynchronous Mode For Better Transi...

Output Voltage Range

0b10: 0.4V to 1.675V

Default Output Voltage

Custom

Output Voltage Tolerance

3 %

(1 - 10)

REDESIGN

SCHEMATIC BILL OF MATERIALS

Click a component to find out more information or select an alternate part.

WEBENCH Power Designer Inputs

Customize TPS6287B25LA0WRZV - 2.7V-6V to .75V @ 19.5A

Input: DC 4.5 V - 5.5 V Output: 0.8 V at 19.5 A Temp: 30 °C [Change](#)

[SELECT](#)

[CUSTOMIZE](#)

[SIMULATE](#)

[EXPORT](#)

Summary

Efficiency: 89.7%
BOM Cost: \$4.68
Footprint: 311 mm²

[CHANGE OPTIMIZATION](#)

Configuration Options

Mode of Operation

FPWM

☐ Custom Sync Frequency

Sync Frequency
1.5 MHz
(1.3 - 1.8)

☐ Asynchronous Mode For Better Transi...

Output Voltage Range
0b10: 0.4V to 1.675V

Default Output Voltage
Custom

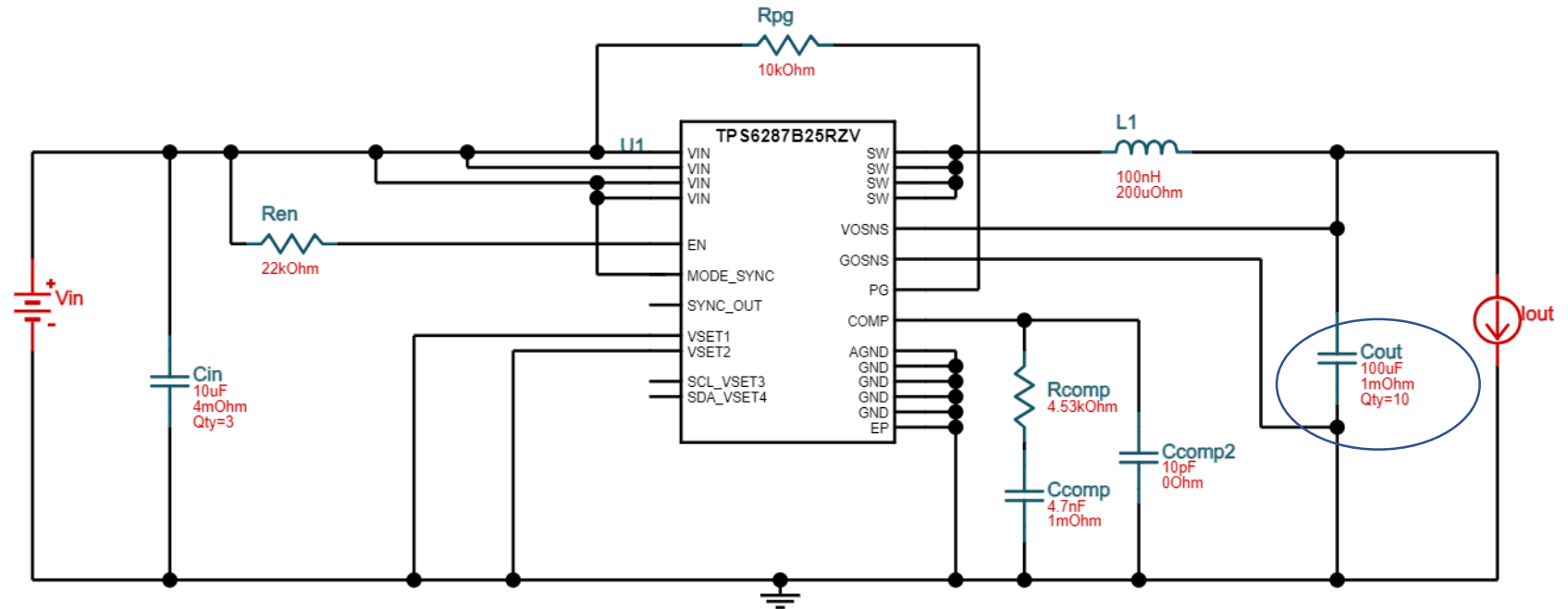
Output Voltage Tolerance
2 %
(1 - 10)

[REDESIGN](#)

[SCHEMATIC](#)

[BILL OF MATERIALS](#)

Click a component to find out more information or select an alternate part.



Load Transient : ~20% peak to peak improvement

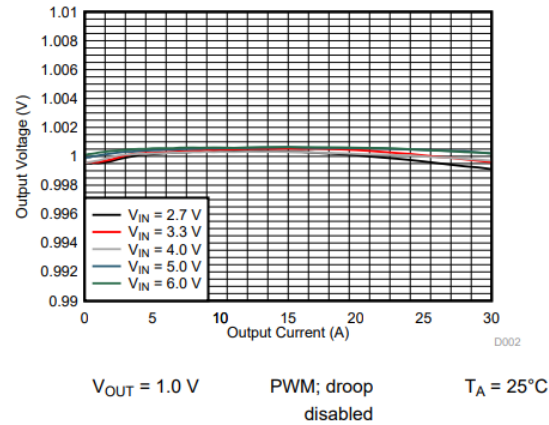


Figure 9-12. Output Voltage Versus Output Current

Droop disabled

$$\Delta V_{OUT} = 34 \text{ mV}_{pp}$$

$$\text{AC+DC spec}$$

$$C_{OUT} = 2 \cdot 330 + 3 \cdot 100 + 2 \cdot 47 + 10 + 1 \mu\text{F}$$

$$= 1065 \mu\text{F}$$

Recommended

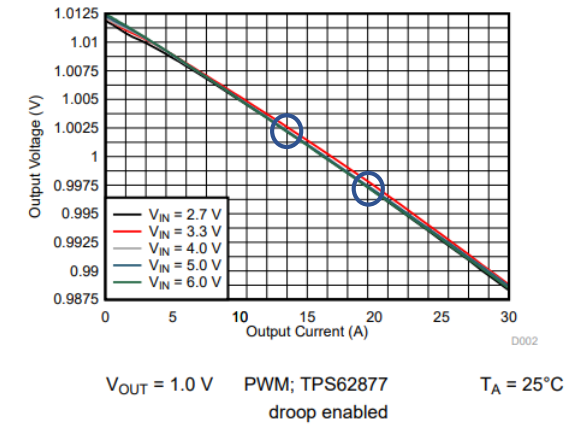
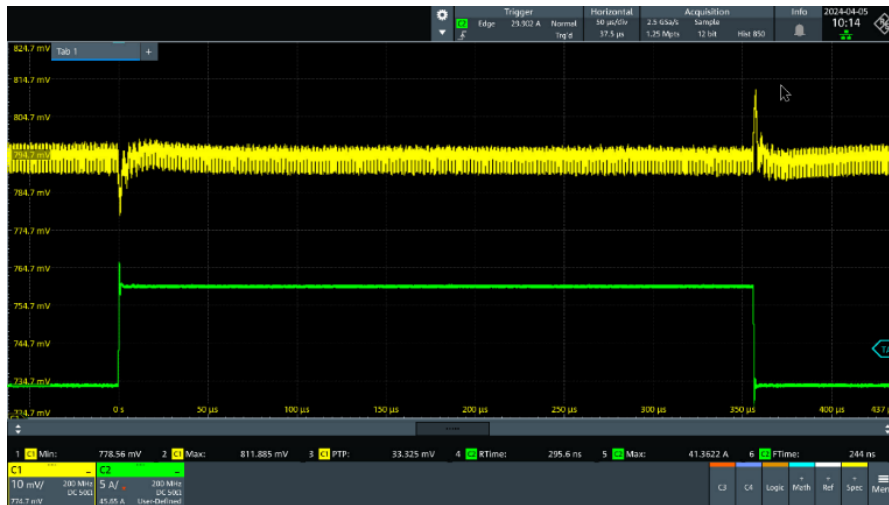


Figure 9-13. Output Voltage Versus Output Current

Droop enabled



$$\Delta V_{OUT} = 33.3 \text{ mV peak to peak}$$

TI EVM

Load Step 26A↔39A
200A/us, Vout=0.80V



$$\Delta V_{OUT} = 25.8 \text{ mV peak to peak}$$

Load Transient: ~-40% output capacitance reduction

$$\Delta V_{OUT} = 34 \text{ mV}_{pp}$$

AC+DC spec

$$C_{OUT} = 4 \cdot 100 + 4 \cdot 47$$

$$+ 10 + 1 \mu\text{F}$$

= 599 μF Recommended

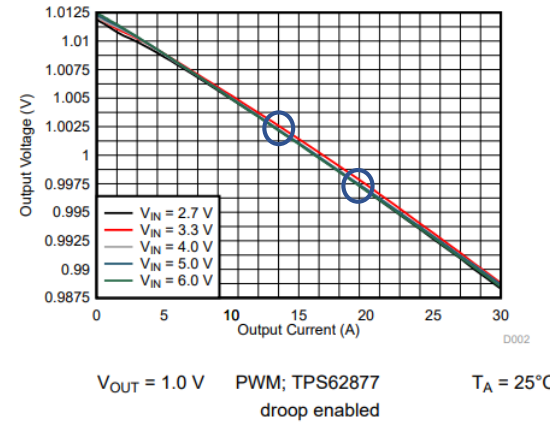


Figure 9-13. Output Voltage Versus Output Current

Droop enabled

TI EVM

Load Step 26A \leftrightarrow 39A

200A/ μs , $V_{out}=0.80\text{V}$



$$\Delta V_{OUT} = 30.7 \text{ mV peak to peak}$$

WEBENCH Power Designer Inputs

Export Design Report

Customize TPS6287B25LA0WRZV - 4.5V-5.5V to .80V @ 19.5A

Input: DC 4.5 V - 5.5 V Output: 0.8 V at 19.5 A Temp: 30 °C [Change](#)

SELECT

CUSTOMIZE

SIMULATE

EXPORT

Summary

| | |
|-------------|---------------------|
| Efficiency: | 89.7% |
| BOM Cost: | \$4.68 |
| Footprint: | 311 mm ² |

CHANGE OPTIMIZATION

Configuration Options

Mode of Operation

FPWM

☐ Custom Sync Frequency

Sync Frequency

MHz

~~(1.2 1.8)~~

☐ Asynchronous Mode For Better Transi...

Output Voltage Range
0b10: 0.4V to 1.675V

Default Output Voltage

Custom

Output Voltage Tolerance

2

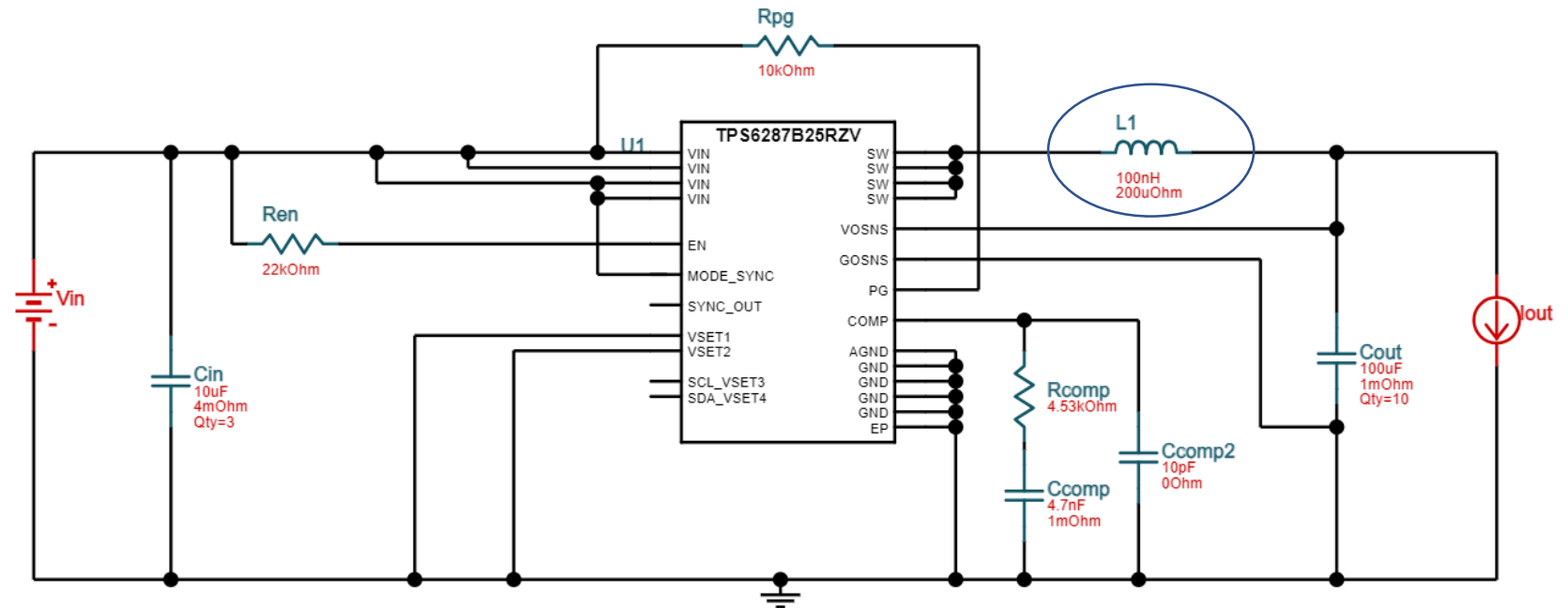
(1 - 10)

REDESIGN

SCHEMATIC

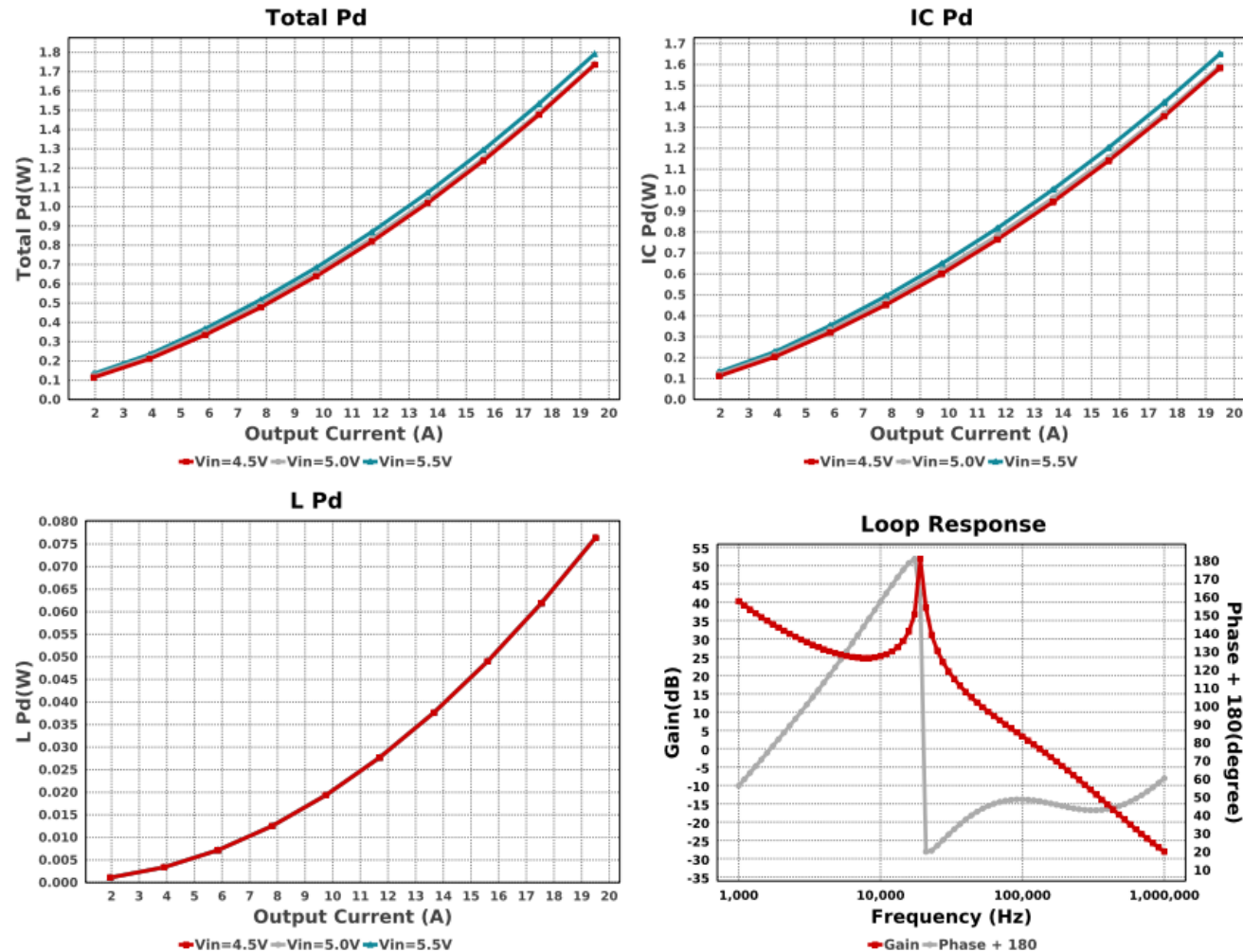
BILL OF MATERIALS

Click a component to find out more information or select an alternate part.



WEBENCH Power Designer Outputs

Design Report



Summary

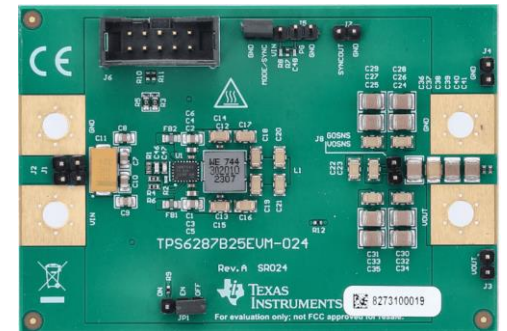
- The Main contributor for the use a large output capacitance bank is the load requirements of your processor
- Webench can help the bring up of your design by tuning your load transient requirements
- Stacking (paralleling), remote sense and tight DC accuracy are important for processor power
- Features such as Droop compensation can help improve your load transient performance and reduce your output capacitance up to 40%

Some featured products

AMD Versal™ AI Edge Series



Texas Instruments TPS6287B25, 25-A Step-Down Converter



**Wuerth Elektronik
74435030010 Series Ultra-Low Loss Shielded
Power Inductors**



Low entry access to electronics design with REDEXPERT®

Navigate by order code

Enter at least first 4 characters

Design Tools



EMI Filter Designer



MagI³C Power Module Designer



Resonance Tank Calculation for Wireless Power



Filter Circuits



DC/DC Converter



Flyback Transformer



AC/DC Converter



Wireless Connectivity and Sensors

Product selection



EMC Components



Power Inductors and Magnetics



MagI³C Power Products



Signal & Communications



Capacitors & Resistors



Optoelectronics



Quartz Crystals & Oscillators



EMC Shielding & Grounding



Filter Designer shows the output impedance for many load impedances

Our EMI Filter Designer shows the output impedance for a variety of different load / LISN impedances from 0 up to 10 Ohms.

| W | H _{Max} | T _{Op} | Shielded | AEC-Q |
|---------|------------------|-----------------|----------|-------|
| 1.60 mm | 1.00 mm | 125°C | Shielded | × |
| 1.60 mm | 1.00 mm | 125°C | Shielded | × |
| 1.60 mm | 1.00 mm | 125°C | Shielded | × |
| 1.60 mm | 1.00 mm | 125°C | Shielded | × |
| 1.60 mm | 1.00 mm | 125°C | Shielded | × |
| 1.60 mm | 1.00 mm | 125°C | Shielded | × |

Bookmark the actual module

Add the actual module to your favorites (Login required), to have quick access directly on the REDEXPERT start page. Warning: It might save you time!

Register / Log In

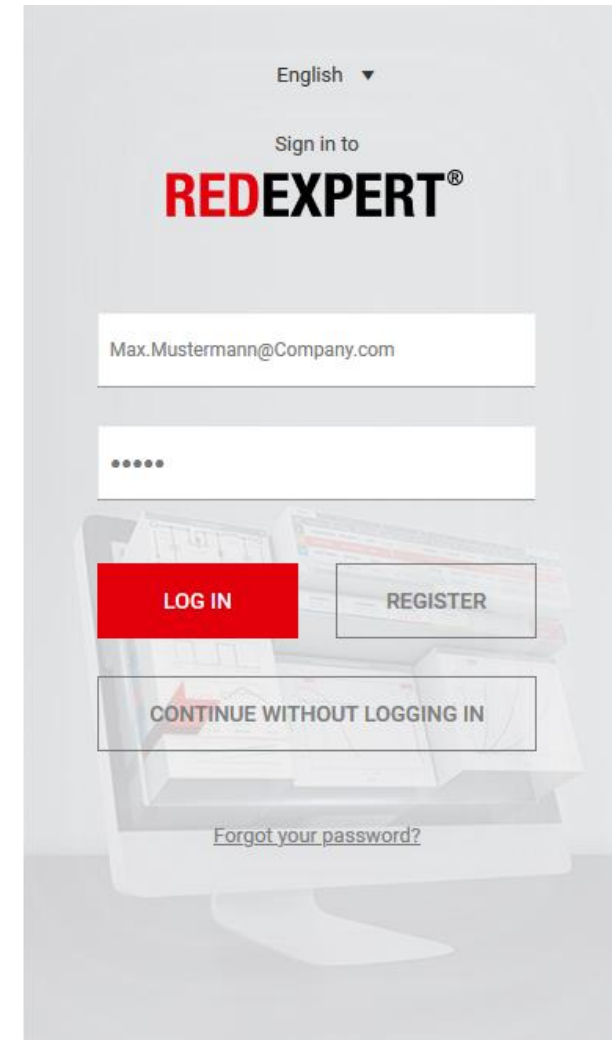
Or continue without logging in

- Registration is not mandatory
- All basic functions are available without logging in
- Registration, use and enjoyment are totally **free of charge**
- A user account does have its perks:
 - Order free samples directly from the app
 - Using of sliders for advanced search queries

Privacy Concerns

Your personal information is stored according to GDPR rules

We need your contact information for the samples and offers only



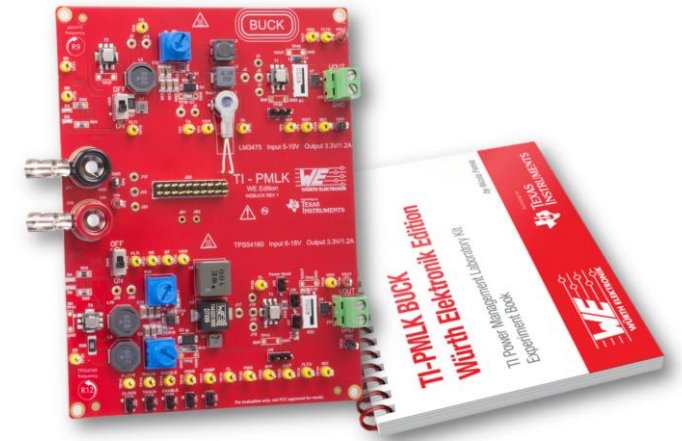
Power Inductor Selection

Output Inductor Selection (L_O)

To calculate the minimum value of the output inductor, use

$$L_{O(min)} = \frac{V_{IN(max)} - V_{OUT}}{I_{OUT} \times K_{IND}} \times \frac{V_{OUT}}{V_{IN(max)} \times f_{sw}}$$

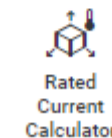
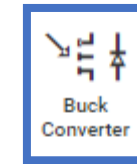
K_{IND} is a coefficient that represents the amount of inductor ripple current relative to the maximum output current



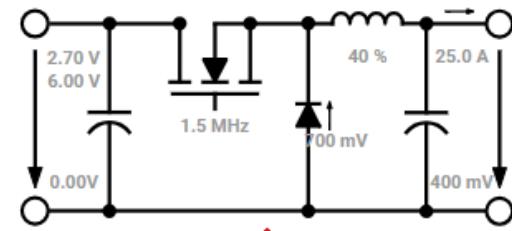
https://www.we-online.com/en/components/products/DESIGNKIT_744732

Power Inductor Selection

- With **REDEXPERT** you can select a power inductor based on you application
- It will need the following paramters of your SMPS:
 - Input / Output Voltage
 - Output Current
 - Switching Frequency
 - Ripple factor (in %)
 - Diode Voltage (Optional)



PARAMETERS



The circuit diagram shows a Buck Converter topology. It includes an input voltage source with a range of 2.70 V to 6.00 V, a MOSFET switch, a freewheeling diode, an inductor with a ripple factor of 40 %, and an output capacitor. The output current is 25.0 A. The switching frequency is 1.5 MHz. The diode forward voltage is 0.700 mV. The output voltage is 0.400 mV.

Topology

☐ Sync

☒ Non Sync

Input

$V_{in,min}$ 2.7 V $V_{in,max}$ 6 V

Output

V_{out} 0.4 V I_{out} 25 A

Switch

f_{sw} 1.5 MHz

Inductor

ΔI_L 40 % Show Suitable ▼

Diode

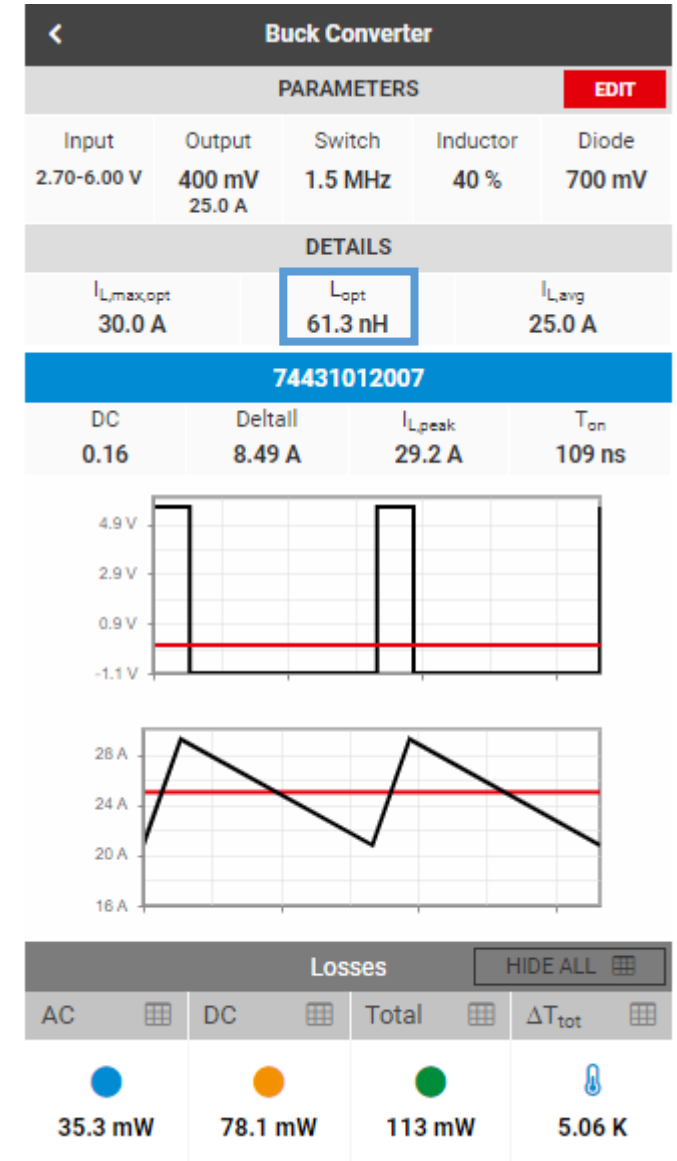
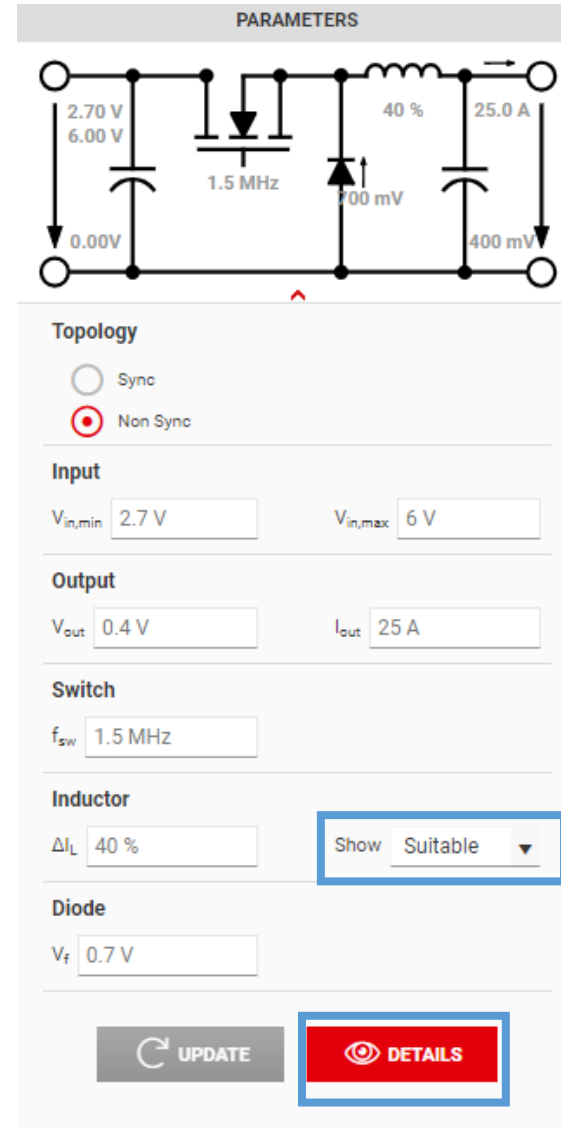
V_f 0.7 V

UPDATE DETAILS

Power Inductor Selection

REDEXPERT will not only find all suitable inductors but will also calculate the expected losses and temperature rise with high accuracy

Suggestion: The „perfect“ inductance wont exist anyway, order a sample for one inductance value above and below your results



Losses

| Order Code | Series | Size | L... | Spec | Type | L ₀ | L _{20.0°C@25.0 A} | R _{DC,typ} | ΔI _L | I _R | I _{sat} | V _p | f _{res} | P _{AC,L} | P _{DC,L} | P _{TOT,L} | ΔT _{T...} |
|-------------|--------|------|------|------|--------|----------------|----------------------------|---------------------|-----------------|----------------|------------------|----------------|------------------|-------------------|-------------------|--------------------|--------------------|
| 74431012007 | WE-HCM | 1012 | | PDF | Single | 70.0 nH | 72.2 nH | 0.125 mΩ | 34.0 % | 84.3 A | 125 A | 80.0 V | 149 MHz | 35.3 mW | 78.1 mW | 113 mW | 5.06 K |
| 744302007 | WE-HCM | 7050 | | PDF | Single | 72.0 nH | 66.4 nH | 0.235 mΩ | 36.9 % | 76.1 A | 64.0 A | 80.0 V | 150 MHz | 1.36 W | 147 mW | 1.51 W | 55.3 K |



74431012007 ✕
744302007 ✕
Click and type or drop an Order Code here

<https://we-online.com/re/5gRQ42Zw>

Core Losses (AC)

Steinmetz Method

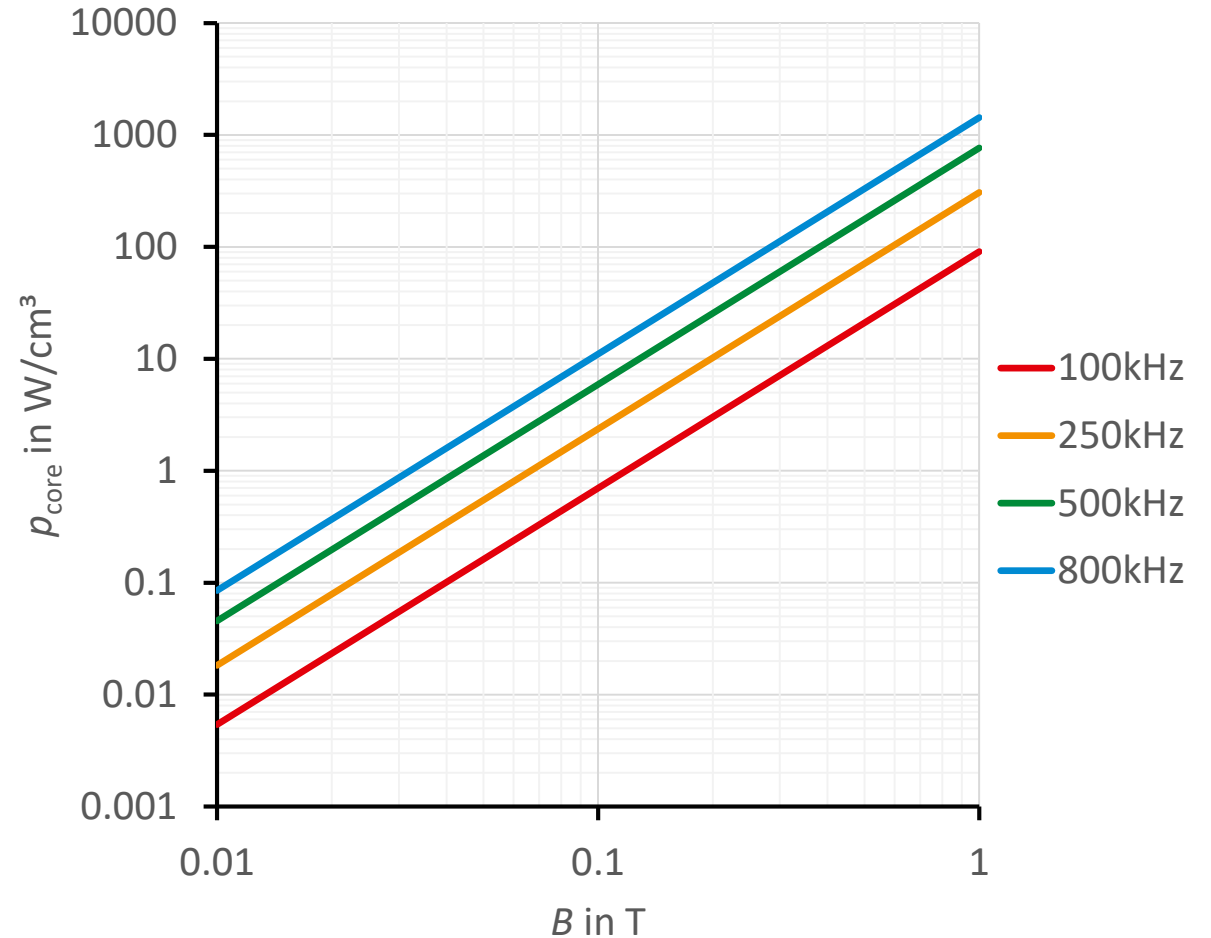
- The Steinmetz Method is a formula to calculate the core losses
- It's based on empirical parameters, measured for toroidal core inductors

$$p_{core} = k * f^a * \hat{B}^b$$

$$k = 7,62 \cdot 10^{-14}$$

$$a = 1,325$$

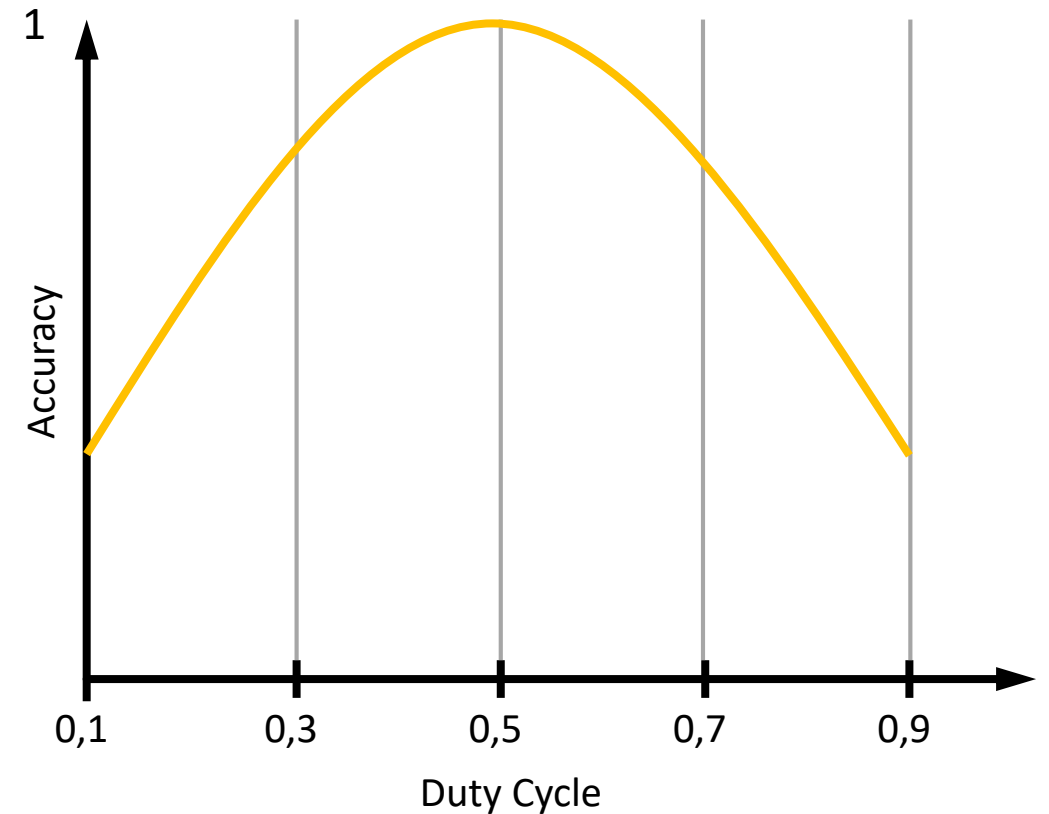
$$b = 2,113$$



Core Losses (AC)

Steinmetz Method

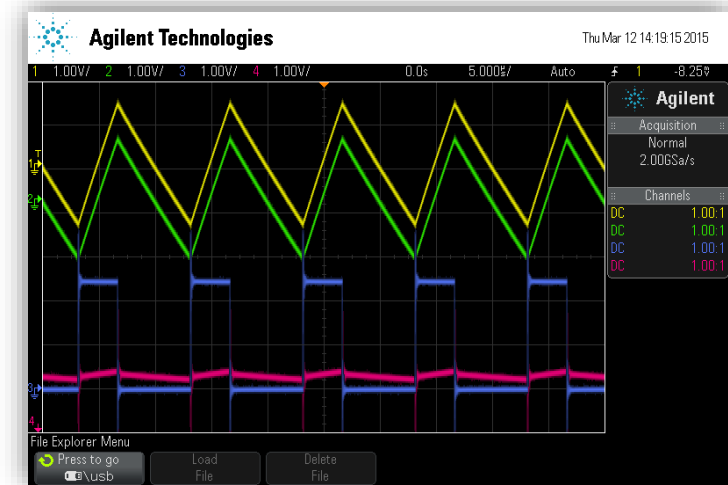
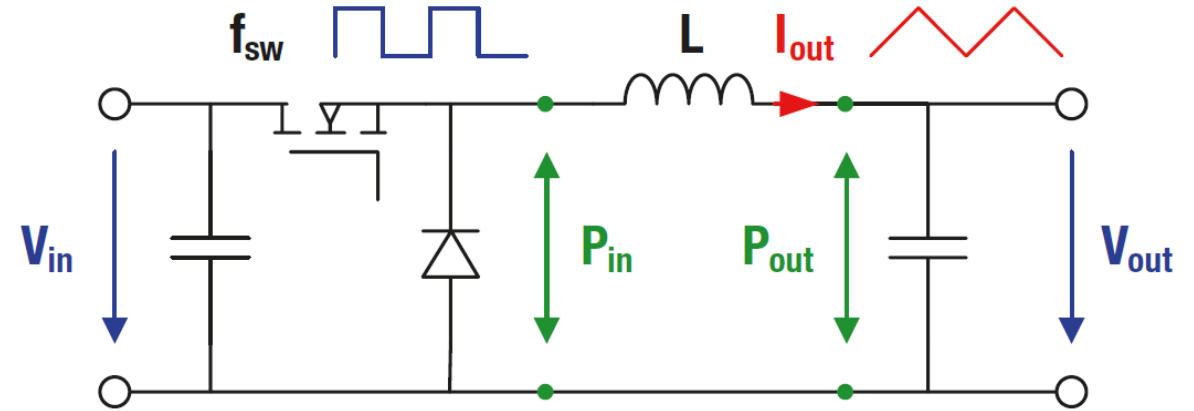
- Steinmetz Parameters are only conditionally valid for real power inductors
- The accuracy is okay for a duty Cycle of 50% but deteriorates quickly in both directions
- A modified Steinmetz Approach takes into account non-sinusoidal excitation of the core:
 - $p_{core} = k * f_{eq}^{a-1} * \hat{B}^b * f$
- Manufacturers have a different model to estimate core losses



Inductor Losses

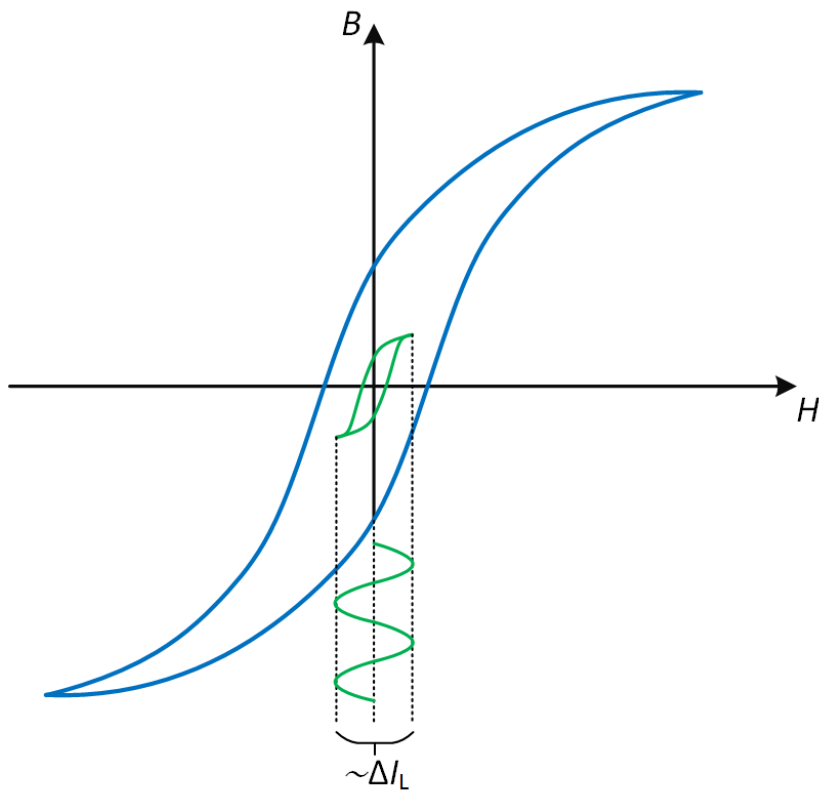
RedExpert:

- Würth Elektronik uses specialized measurement equipment (Buck Converter + Class-D-Amplifier).
- A huge set of parameters is measured in an actual application like setting
- Losses can then be calculated quite easy
 - $P_L = P_{in} - P_{out}$
- Operating Point → **triangle** signal



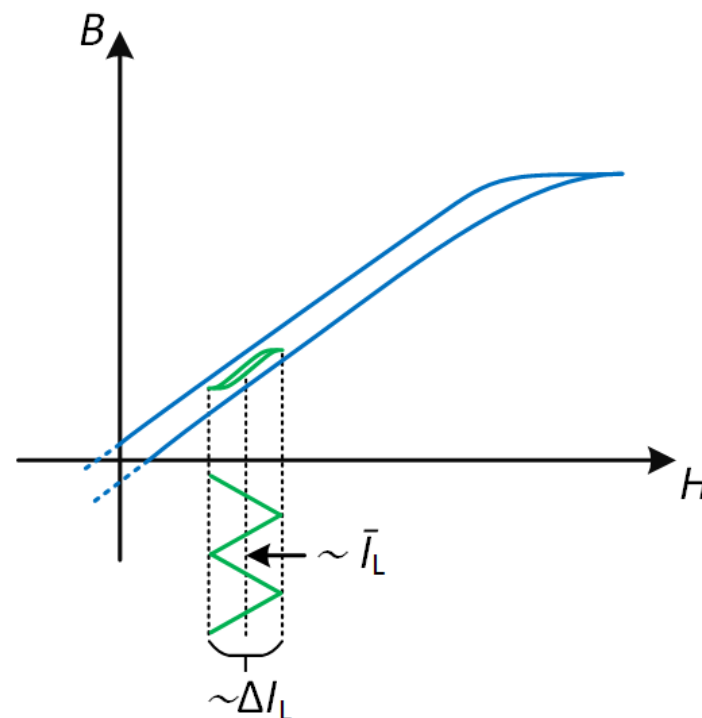
Inductor Losses

Comparison of Operating Point Conditions



Steinmetz

Sinusoidal Excitation, Core Losses only



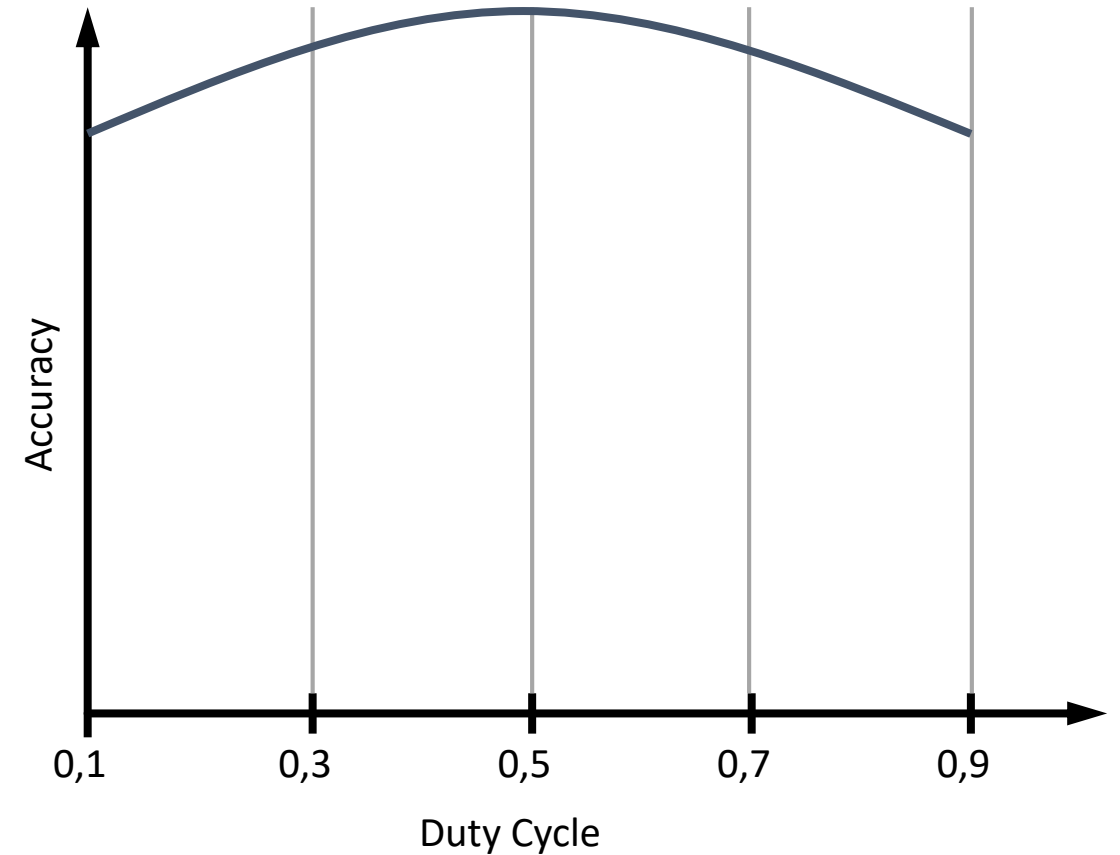
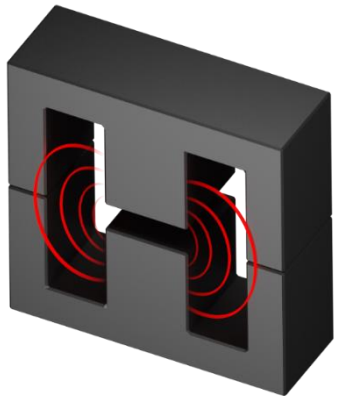
RED EXPERT

Real Operating Point, Total Losses

Inductor Losses

Accounting for

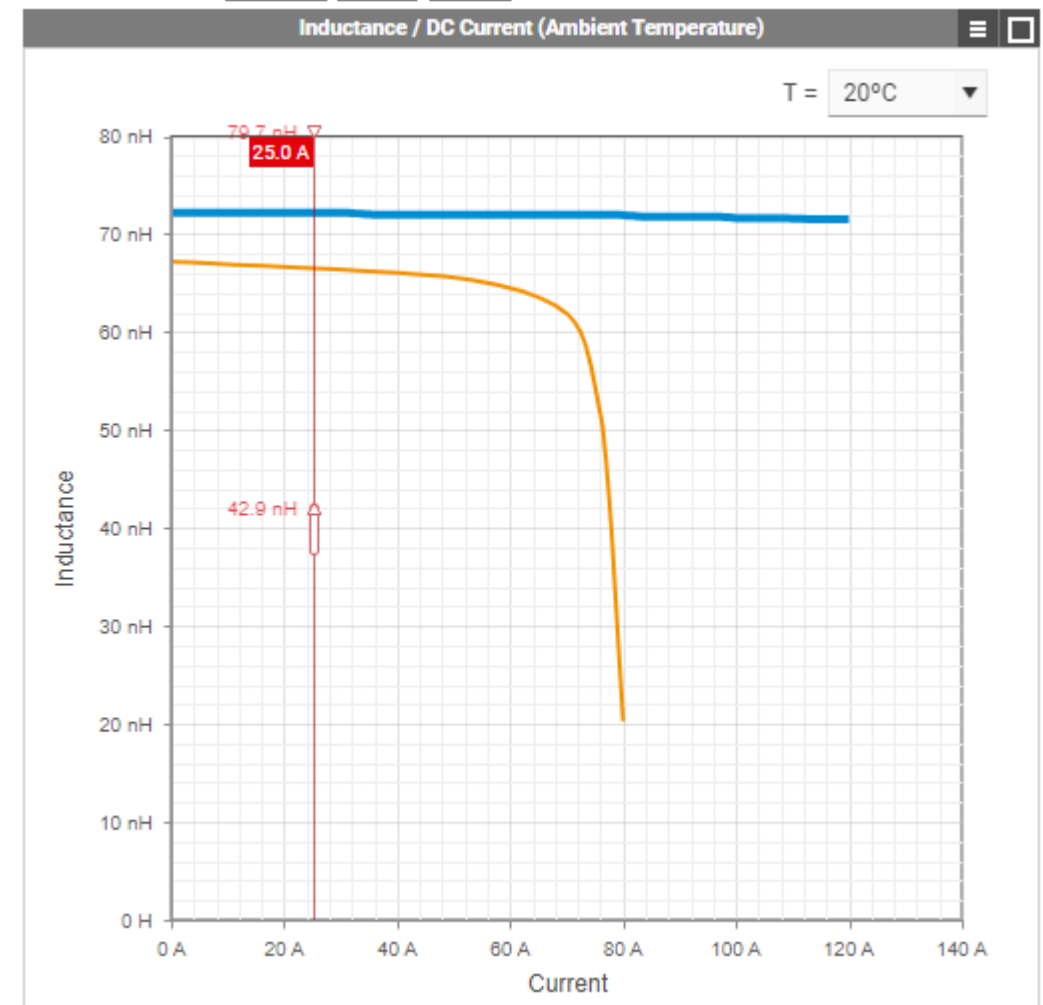
- Real Core geometry
- Stray field effects at the air gap
- Winding structure,
- Material composition,
- AC Losses in the wire



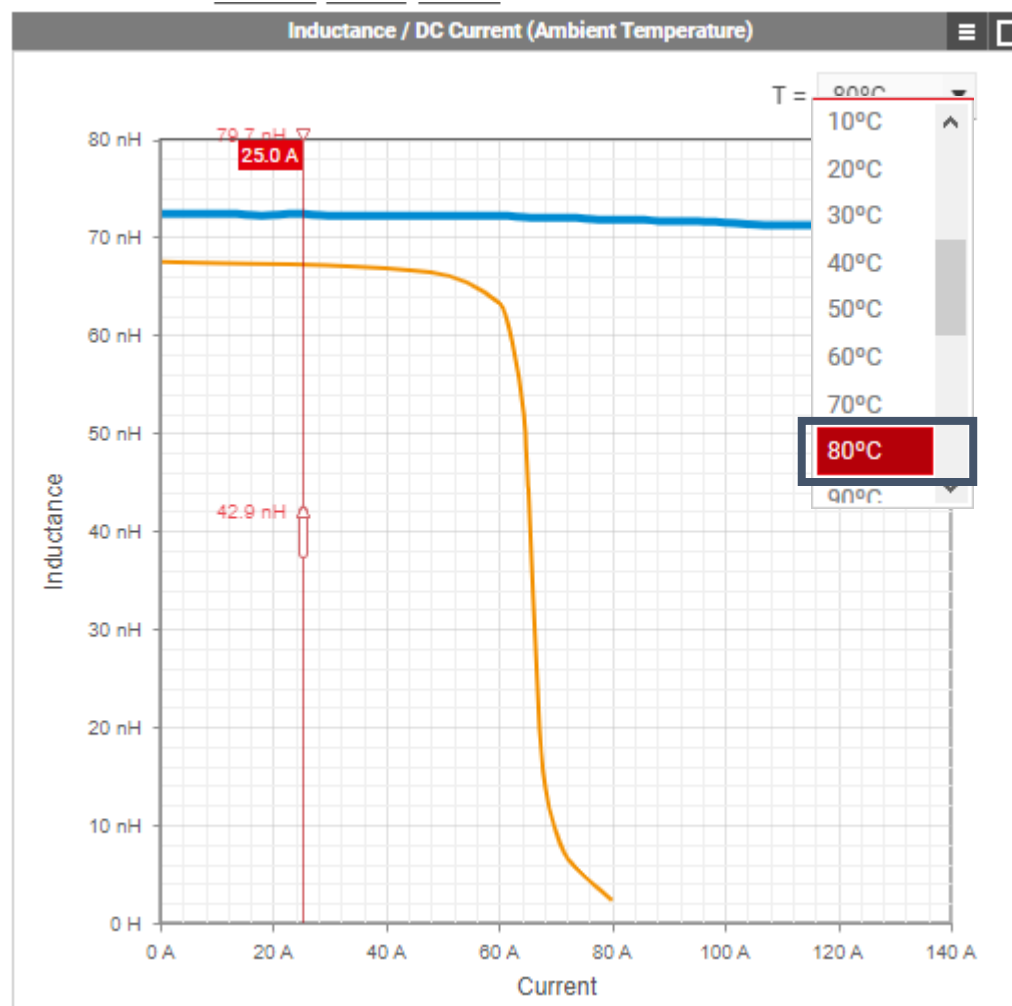
REDEXPERT

Beware the Saturation!

- RedExpert will rely on the rated inductance to calculate the ripple
- Inductance roll-off by saturation
- Saturation Roll_off is not standardized and can vary 10...35% percent between different Series
- Using the Slider, you can verify the actual inductance under operating conditions



Saturation vs. Temperature



Mind the Saturation!

- Datasheet!
- Power Inductors do have tolerances up to 30%
- Saturation effects and Tolerances have to be considered

Electrical Properties:

| Properties | | Test conditions | Value | Unit | Tol. |
|---|-----------------|-----------------------|-------|------|------|
| Inductance | L | 100 kHz/ 100 mA | 72 | nH | ±20% |
| Rated Inductance | L_R | 100 kHz/ 10mA/ 30.0 A | 71 | nH | typ. |
| Rated Current | I_R | $\Delta T = 40$ K | 30 | A | max. |
| Performance Rated Current ¹⁾ | $I_{RP,40K}$ | $\Delta T = 40$ K | 76.1 | A | max. |
| Saturation Current @ 10% | $I_{SAT, 10\%}$ | $ \Delta L/L < 10$ % | 62 | A | typ. |
| Saturation Current @ 30% | $I_{SAT, 30\%}$ | $ \Delta L/L < 30$ % | 64 | A | typ. |
| DC Resistance | R_{DC} | @ 20 °C | 0.235 | mΩ | ±7% |
| Self Resonant Frequency | f_{res} | | 150 | MHz | typ. |

¹⁾ refer to IEC 62024-2-2020

Temperature rise / DC current

PCB: 336 mm³ Ambient Temperature: 20 °C

The graph displays the relationship between DC current and temperature rise for a PCB with a volume of 336 mm³, assuming an ambient temperature of 20 °C. The x-axis represents Current in Amperes (A), ranging from 0 to 120 A. The y-axis represents Temperature Rise in Kelvin (K), ranging from 0 to 100 K. The curve shows that the temperature rise increases non-linearly with current, starting at 0 K for 0 A and reaching approximately 90 K at 110 A.

| Current (A) | Temperature Rise (K) |
|-------------|----------------------|
| 0 | 0 |
| 20 | ~2 |
| 40 | ~10 |
| 60 | ~25 |
| 80 | ~45 |
| 100 | ~70 |
| 110 | ~90 |

Filter Design

EMI Filter Designer for differential mode:

Use this application to design a discrete electronic EMI filter for conducted differential noise, for example from your DC-DC converter, and evaluate the realistic response based on real components.

Project's Title:

Title
My EMI Filter project

Input parameters:

Operating voltage
12 V

Operating current
0.5 A

Load / LISN impedance
100 Ω

Noise source impedance
0.1 Ω

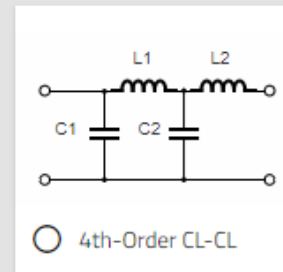
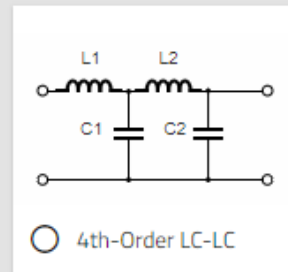
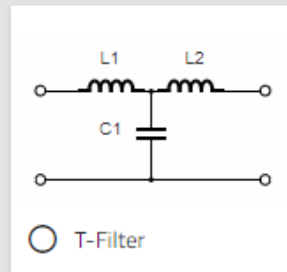
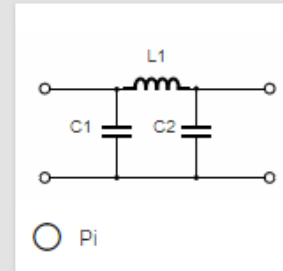
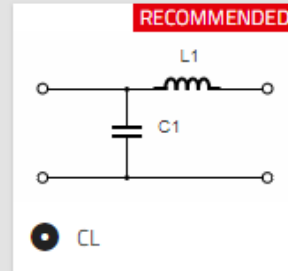
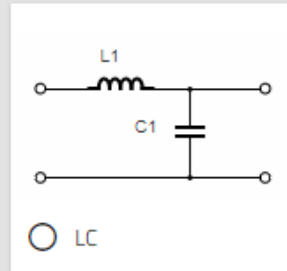
Cut-off frequency
☐ 100 kHz

i Cut-off frequency:
20 kHz

Attenuation
☒ 20 dB

at Frequency
200 kHz

Topology:



Advanced

- ☐ SMD components only
- ☐ Shielded inductors only
- ☐ High temperature (125°C)
- ☐ Shared input capacitor DC/DC converter

C1/C2
10 μ F

Q&A Session



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